Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{RM}	60	V
Average Rectified Output Current	I_O	8	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	280	A
Repetitive Peak Avalanche Power (1µs, +25°C)	P_{ARM}	5,000	W

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Thermal Resistance Junction to Soldering (Note 6) Thermal Resistance Junction to Ambient (Note 7)	 $R_{\theta JS}$ $R_{\theta JA}$	 3 60	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V_F	— — —	0.30 0.46 —	0.35 0.53 0.5	V	I_F = 1.0A, T_J = +25°C I_F = 8A, T_J = +25°C I_F = 8A, T_J = +125°C
Leakage Current (Note 8)	I_R	— —	0.12 —	0.6 100	mA	V_R = 60V, T_J = +25°C V_R = 60V, T_J = +125°C

Notes: 6. Theoretical $R_{\theta JS}$ calculated from the top center of the die straight down to the PCB cathode tab solder junction.
7. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com.
8. Short duration pulse test used to minimize self-heating effect.

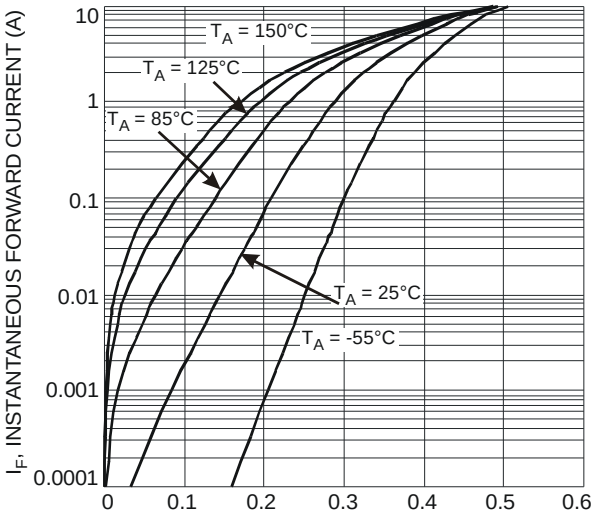


Fig.1 Typical Forward Characteristics

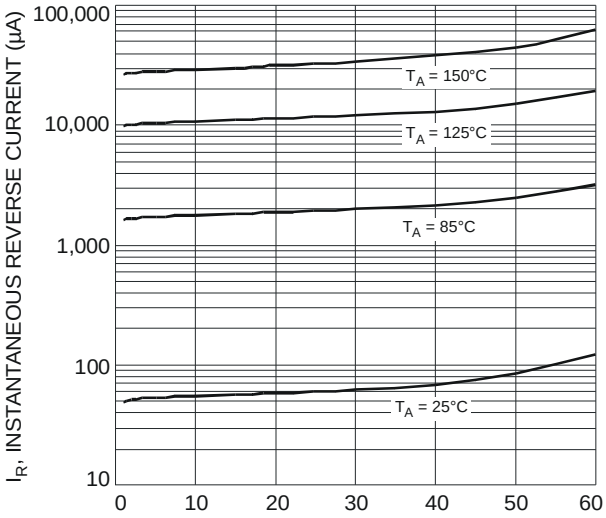


Fig. 2 Typical Reverse Characteristics

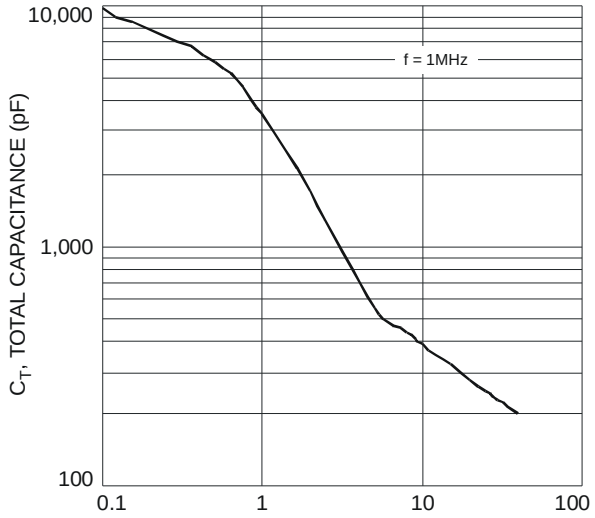


Fig. 3 Typical Total Capacitance

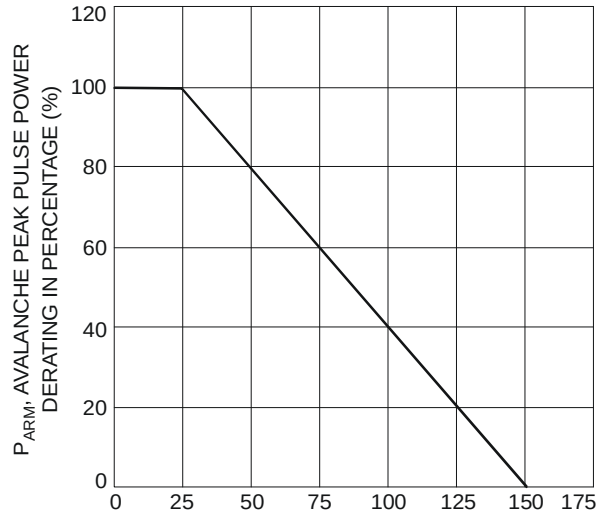


Fig. 4 Pulse Derating Curve

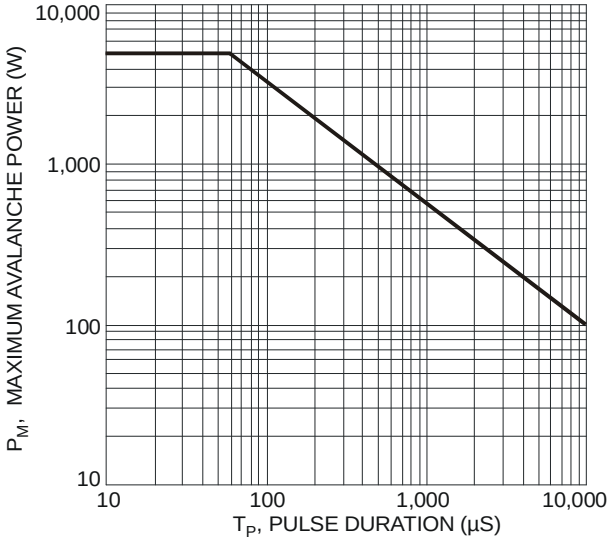


Fig. 5 Maximum Avalanche Power vs. Pulse Duration

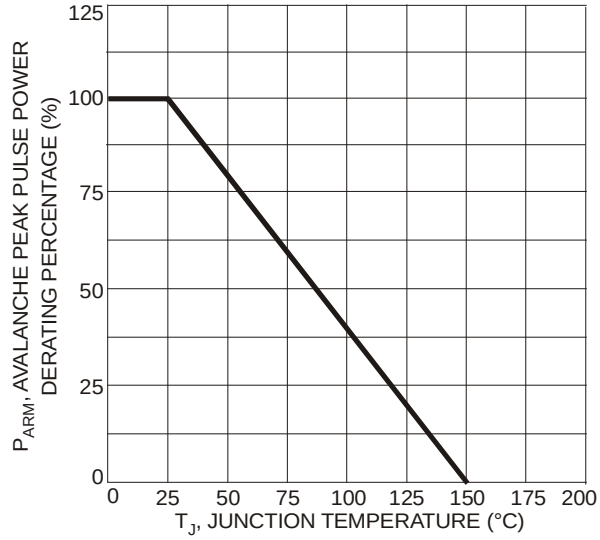


Fig. 6 Pulse Derating Curve

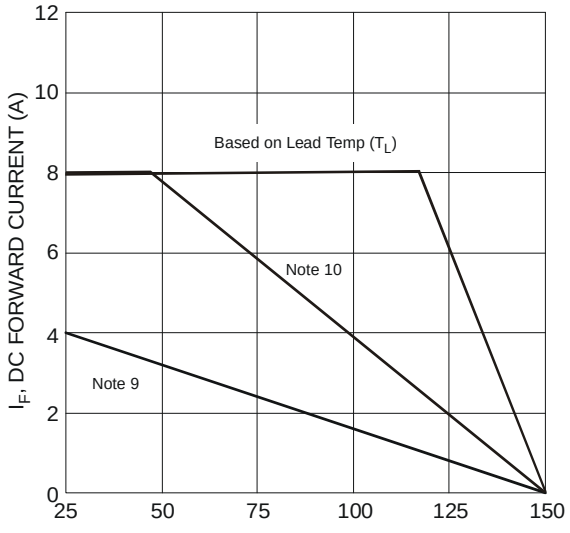


Figure 7 DC Forward Current Derating Curve

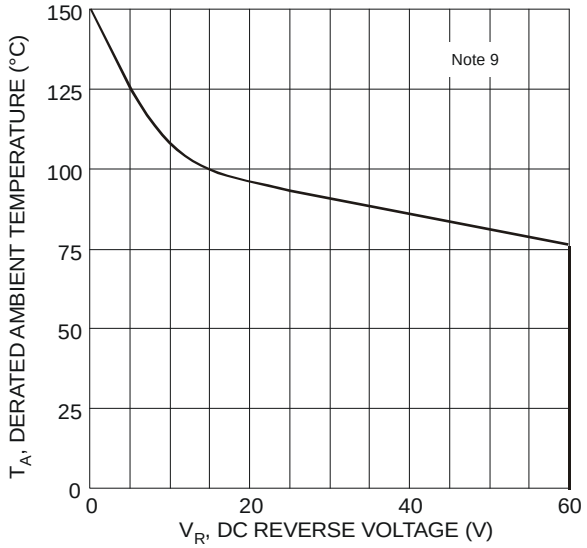
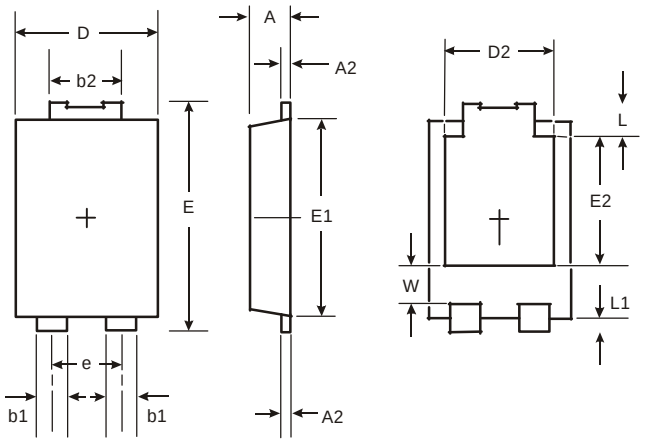


Figure 8 Operating Temperature Derating

Notes: 9. Device mounted on FR-4 substate, 2oz copper, with minimum recommended pad layout.
10. Device mounted on FR-4 substate, 2oz copper, with 10cm x 10cm pad layout.

Package Outline Dimensions

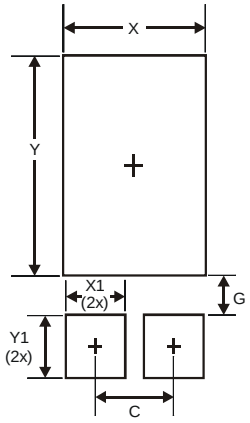
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



POWERDI5		
Dim	**Min**	**Max**
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.054 Typ	
E	6.40	6.60
e	1.84 Typ	
E1	5.30	5.45
E2	3.549 Typ	
L	0.75	0.95
L1	0.50	0.65
W	1.10	1.41
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	1.840
G	0.852
X	3.360
X1	1.390
Y	4.860
Y1	1.400

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